瀚荃股份有限公司
CviLux Corporation

ENGINEERING DEPT.	PRODUCT SPECIFICATION For High Density Solder Dip D-Sub Connector of System CD01	SPEC.NO.: SPCD001E PAGE: 1 / 3

1. SCOPE:
   This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: **CD01 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

   See attached drawings

5. MATERIALS

   See attached drawings

6. SOLDER CUP ACCEPTS CABLE: AWG #20 Max.

CVILUX CORP.
2007.01.30
ISSUED

REVIEWED : Alex APPROVED : David VERIFIED : Sun .

ENGINEERING DEPT.	PRODUCT SPECIFICATION For High Density Solder Dip D-Sub Connector of System CD01	SPEC.NO.: SPCD001E PAGE: 2 / 3

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 5000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute from housing	More than 4.0 Kgf
8.2	Single contact insertion force	Measure force to insertion using ∅ 0.78 mm test pin at speed 25± 3 mm per minute	240 gram max.
8.3	Single contact withdrawal force	Measure force to withdrawal using ∅ 0.74 mm test pin at speed 25± 3 mm per minute	15 gram min.
8.4	Durability	Connector shall be subjected to 100 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solder ability	**Tin-Lead Process:** Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5°C **Lead-Free Process:** Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area

ENGINEERING DEPT.	PRODUCT SPECIFICATION For High Density Solder Dip D-Sub Connector of System CD01	SPEC.NO.: SPCD001E PAGE: 3 / 3

	ITEM	TEST CONDITION	REQUIREMENT
9.4	Hand Soldering	Use a soldering iron that has a sufficient head capacity and high stability of temperature. The tip of the iron should be shaped so as not to touch the part body directly. Temperature : 380±10℃ 3Sec.	No damage
9.5	Heat aging	105 ± 2°C , 96 hours	No damage
9.6	Humidity	40 ± 2°C , 90-95% RH , 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.7	Temperature cycling	One cycle consists of : (1) -55 $^{+0}_{-3}$ °C , 30 min. (2)Room temp. 10-15 min. (3) 85 $^{+3}_{-0}$ °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.8	Salt spray	Temperature: 35 ± 3°C Solution: 5 ± 1% Spray time: 48 ± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -40 to + 105°C

11. MATING FORCE AND UNMATING FORCE:

Unit: Kgf

No. of Circuits	Mating Force (Initial max.)	Unmating Force (Initial max.)
15	5.1	3.8
26	9.2	6.9
44	12.6	8.6
62	16.4	10.8